



Initial Process/Product Change Notification

IPCN No: 2011-001
Date: 7th July 2011
Subject: Change of subcontractor for die sourcing and device assembly of the MSMB/MSMC/MSML part family.

Purpose:

This correspondence is advance notification of the above product / process change. A PCN will be issued 30 days prior to implementation, and will contain qualification and characterisation data.

Description of Change:

This correspondence is official notice communicating the intended change of die source and assembly process for the Microsemi manufactured parts listed below. The intended date of first shipment is 1st September 2011.

Open Orders:

All currently scheduled orders shall be delivered per the dates reflected in the Order Acknowledgement from Microsemi.

Part Numbers Affected:

All quality levels of:

MSMBJ5.0A thru MSMBJ170CA, e3
MSMCJ5.0A thru MSMCJ170CA, e3
MSMLJ5.0A thru MSMLJ170CA, e3

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